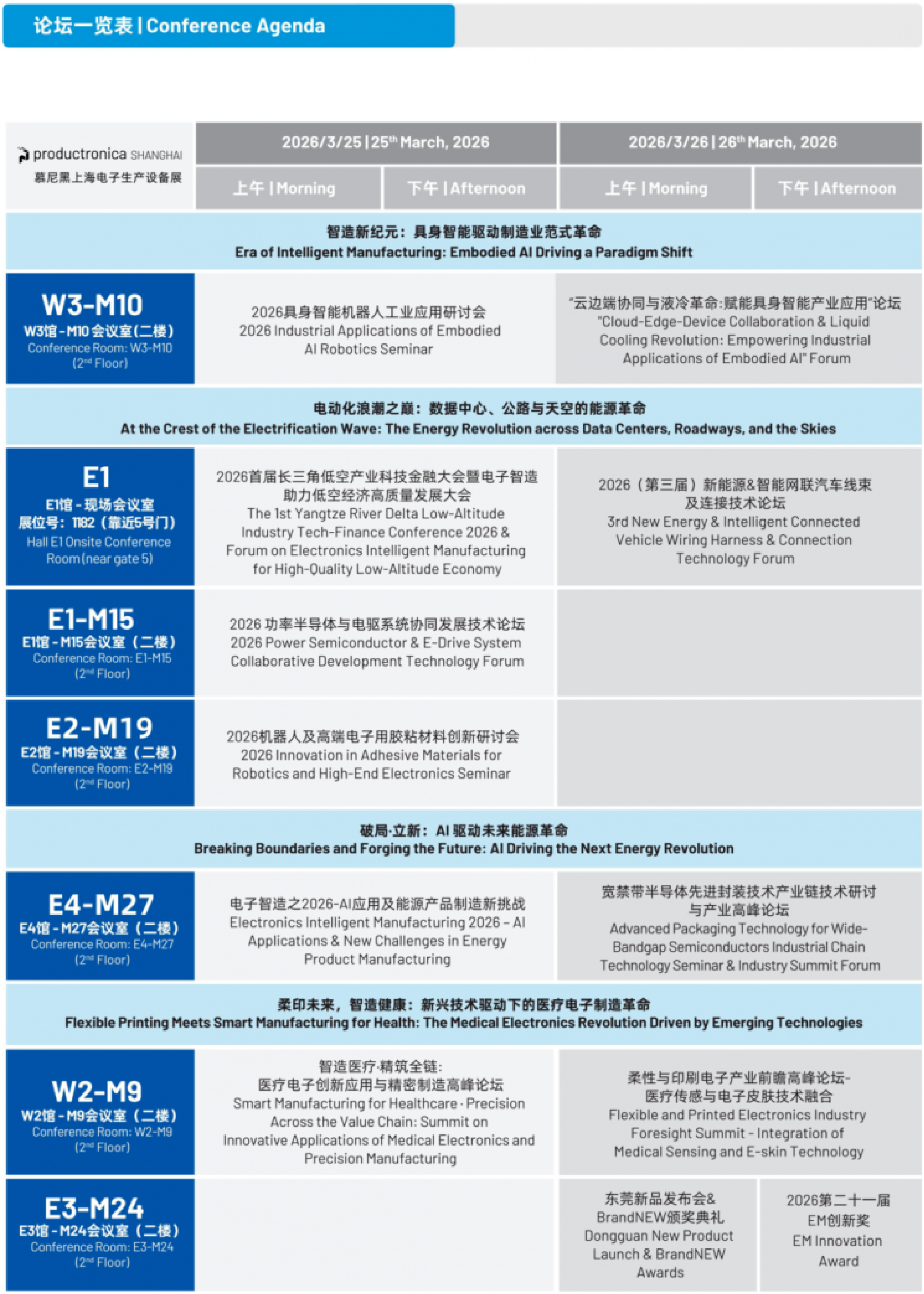
论坛合集 | 展会同期十大主题论坛议程大公布，共探电子智造未来航向！

2026慕尼黑上海电子生产设备展（productronica Shanghai）将在2026年3月25至27日，上海新国际博览中心（E1-E5, W1-W4馆）盛大举办。作为电子制造行业重要的展示与交流平台，本届展会以近100,000平方米展示面积、超1,100家参展企业的规模，聚焦汽车、工业、通讯电子、医疗电子等多领域需求，旨在为行业呈现一场覆盖电子生产全产业链的“ 创新盛宴 ”，重点聚焦智慧工厂、新能源汽车技术及数字化未来。

实名制认证+线上预约，现场免排队

特别提醒：请务必携带好您的身份证前来参观，现场需刷身份证入场！

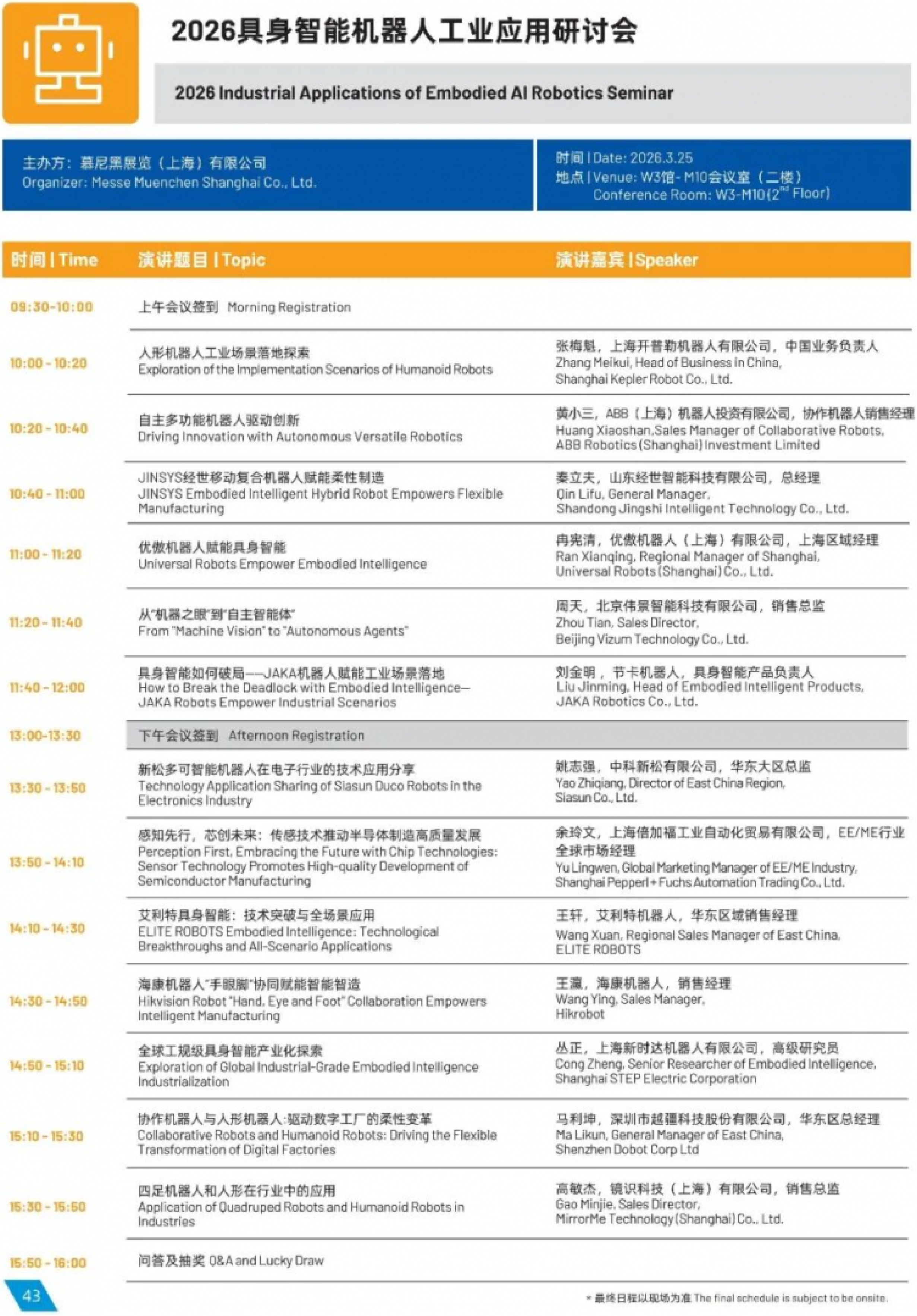
同期论坛一览



论坛一览表 | Conference Agenda

productronica SHANGHAI 慕尼黑上海电子生产设备展	2026/3/25 | 25th March, 2026		2026/3/26 | 26th March, 2026	
	上午 | Morning	下午 | Afternoon	上午 | Morning	下午 | Afternoon
智造新纪元：具身智能驱动制造业范式革命 Era of Intelligent Manufacturing: Embodied AI Driving a Paradigm Shift				
W3-M10 W3馆 - M10 会议室(二楼) Conference Room: W3-M10 (2nd Floor)	2026具身智能机器人工业应用研讨会 2026 Industrial Applications of Embodied AI Robotics Seminar		"云边端协同与液冷革命:赋能具身智能产业应用"论坛 "Cloud-Edge-Device Collaboration & Liquid Cooling Revolution: Empowering Industrial Applications of Embodied AI" Forum	
电动化浪潮之巅：数据中心、公路与天空的能源革命 At the Crest of the Electrification Wave: The Energy Revolution across Data Centers, Roadways, and the Skies				
E1 E1馆 - 现场会议室 展位号：1182（靠近5号门） Hall E1 Onsite Conference Room (near gate 5)	2026首届长三角低空产业科技金融大会暨电子智造助力低空经济高质量发展大会 The 1st Yangtze River Delta Low-Altitude Industry Tech-Finance Conference 2026 & Forum on Electronics Intelligent Manufacturing for High-Quality Low-Altitude Economy		2026（第三届）新能源&智能网联汽车线束及连接技术论坛 3rd New Energy & Intelligent Connected Vehicle Wiring Harness & Connection Technology Forum	
E1-M15 E1馆 - M15会议室（二楼） Conference Room: E1-M15 (2nd Floor)	2026 功率半导体与电驱系统协同发展技术论坛 2026 Power Semiconductor & E-Drive System Collaborative Development Technology Forum			
E2-M19 E2馆 - M19会议室（二楼） Conference Room: E2-M19 (2nd Floor)	2026机器人及高端电子用胶粘材料创新研讨会 2026 Innovation in Adhesive Materials for Robotics and High-End Electronics Seminar			
破局·立新：AI 驱动未来能源革命 Breaking Boundaries and Forging the Future: AI Driving the Next Energy Revolution				
E4-M27 E4馆 - M27会议室（二楼） Conference Room: E4-M27 (2nd Floor)	电子智造之2026-AI应用及能源产品制造新挑战 Electronics Intelligent Manufacturing 2026 - AI Applications & New Challenges in Energy Product Manufacturing		宽禁带半导体先进封装技术产业链技术研讨与产业高峰论坛 Advanced Packaging Technology for Wide-Bandgap Semiconductors Industrial Chain Technology Seminar & Industry Summit Forum	
柔印未来，智造健康：新兴技术驱动下的医疗电子制造革命 Flexible Printing Meets Smart Manufacturing for Health: The Medical Electronics Revolution Driven by Emerging Technologies				
W2-M9 W2馆 - M9会议室（二楼） Conference Room: W2-M9 (2nd Floor)	智造医疗·精筑全链：医疗电子创新应用与精密制造高峰论坛 Smart Manufacturing for Healthcare · Precision Across the Value Chain: Summit on Innovative Applications of Medical Electronics and Precision Manufacturing		柔性与印刷电子产业前瞻高峰论坛-医疗传感与电子皮肤技术融合 Flexible and Printed Electronics Industry Foresight Summit - Integration of Medical Sensing and E-skin Technology	
E3-M24 E3馆 - M24会议室（二楼） Conference Room: E3-M24 (2nd Floor)			东莞新品发布会&BrandNEW颁奖典礼 Dongguan New Product Launch & BrandNEW Awards	2026第二十一届EM创新奖 EM Innovation Award

同期论坛议程公布



2026具身智能机器人工业应用研讨会

2026 Industrial Applications of Embodied AI Robotics Seminar

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.25
地点 | Venue: W3馆- M10会议室（二楼）
Conference Room: W3-M10 (2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:30-10:00	上午会议签到 Morning Registration	
10:00 - 10:20	人形机器人工业场景落地探索 Exploration of the Implementation Scenarios of Humanoid Robots	张梅魁，上海开普勒机器人有限公司，中国业务负责人 Zhang Meikui, Head of Business in China, Shanghai Kepler Robot Co., Ltd.
10:20 - 10:40	自主多功能机器人驱动创新 Driving Innovation with Autonomous Versatile Robotics	黄小三，ABB（上海）机器人投资有限公司，协作机器人销售经理 Huang Xiaoshan,Sales Manager of Collaborative Robots, ABB Robotics (Shanghai) Investment Limited
10:40 - 11:00	JINSYS经世移动复合机器人赋能柔性制造 JINSYS Embodied Intelligent Hybrid Robot Empowers Flexible Manufacturing	秦立夫，山东经世智能科技有限公司，总经理 Qin Lifu, General Manager, Shandong Jingshi Intelligent Technology Co., Ltd.
11:00 - 11:20	优傲机器人赋能具身智能 Universal Robots Empower Embodied Intelligence	冉宪清，优傲机器人（上海）有限公司，上海区域经理 Ran Xianqing, Regional Manager of Shanghai, Universal Robots (Shanghai) Co., Ltd.
11:20 - 11:40	从"机器之眼"到"自主智能体" From "Machine Vision" to "Autonomous Agents"	周天，北京伟景智能科技有限公司，销售总监 Zhou Tian, Sales Director, Beijing Vizum Technology Co., Ltd.
11:40 - 12:00	具身智能如何破局——JAKA机器人赋能工业场景落地 How to Break the Deadlock with Embodied Intelligence—JAKA Robots Empower Industrial Scenarios	刘金明，节卡机器人，具身智能产品负责人 Liu Jinming, Head of Embodied Intelligent Products, JAKA Robotics Co., Ltd.
13:00-13:30	下午会议签到 Afternoon Registration	
13:30 - 13:50	新松多可智能机器人在电子行业的技术应用分享 Technology Application Sharing of Siasun Duco Robots in the Electronics Industry	姚志强，中科新松有限公司，华东大区总监 Yao Zhiqiang, Director of East China Region, Siasun Co., Ltd.
13:50 - 14:10	感知先行，芯创未来：传感技术推动半导体制造高质量发展 Perception First, Embracing the Future with Chip Technologies: Sensor Technology Promotes High-quality Development of Semiconductor Manufacturing	余玲文，上海倍加福工业自动化贸易有限公司，EE/ME行业全球市场经理 Yu Lingwen, Global Marketing Manager of EE/ME Industry, Shanghai Pepperl+Fuchs Automation Trading Co., Ltd.
14:10 - 14:30	艾利特具身智能：技术突破与全场景应用 ELITE ROBOTS Embodied Intelligence: Technological Breakthroughs and All-Scenario Applications	王轩，艾利特机器人，华东区域销售经理 Wang Xuan, Regional Sales Manager of East China, ELITE ROBOTS
14:30 - 14:50	海康机器人"手眼脚"协同赋能智能智造 Hikvision Robot "Hand, Eye and Foot" Collaboration Empowers Intelligent Manufacturing	王瀛，海康机器人，销售经理 Wang Ying, Sales Manager, Hikrobot
14:50 - 15:10	全球工规级具身智能产业化探索 Exploration of Global Industrial-Grade Embodied Intelligence Industrialization	丛正，上海新时达机器人有限公司，高级研究员 Cong Zheng, Senior Researcher of Embodied Intelligence, Shanghai STEP Electric Corporation
15:10 - 15:30	协作机器人与人形机器人:驱动数字工厂的柔性变革 Collaborative Robots and Humanoid Robots: Driving the Flexible Transformation of Digital Factories	马利坤，深圳市越疆科技股份有限公司，华东区总经理 Ma Likun, General Manager of East China, Shenzhen Dobot Corp Ltd
15:30 - 15:50	四足机器人和人形在行业中的应用 Application of Quadruped Robots and Humanoid Robots in Industries	高敏杰，镜识科技（上海）有限公司，销售总监 Gao Minjie, Sales Director, MirrorMe Technology (Shanghai) Co., Ltd.
15:50 - 16:00	问答及抽奖 Q&A and Lucky Draw	

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* 最终日程以现场为准 The final schedule is subject to be onsite.

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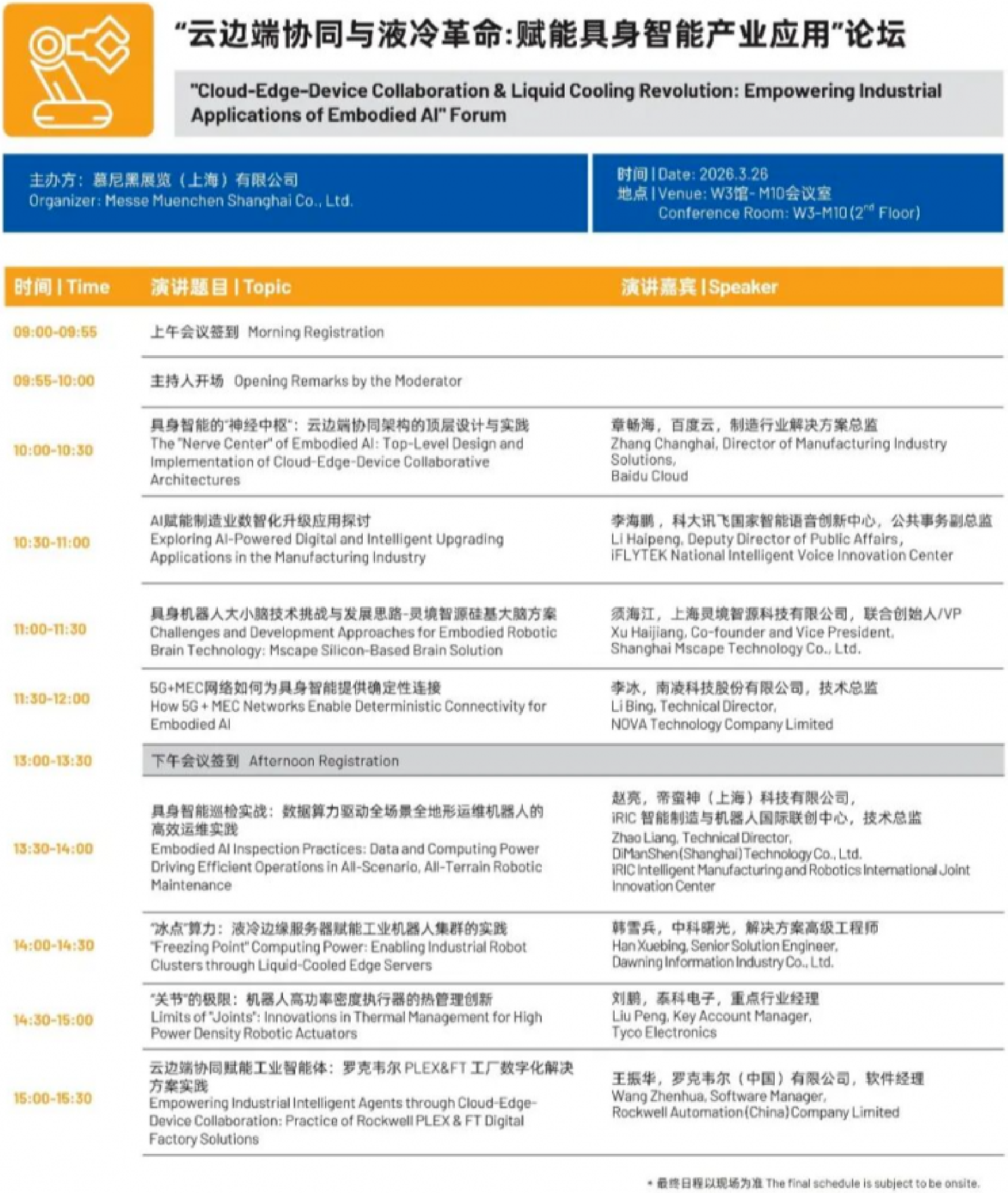

“云边端协同与液冷革命:赋能具身智能产业应用”论坛

"Cloud-Edge-Device Collaboration & Liquid Cooling Revolution: Empowering Industrial Applications of Embodied AI" Forum

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.26
地点 | Venue: W3馆- M10会议室
Conference Room: W3-M10 (2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:00-09:55	上午会议签到 Morning Registration	
09:55-10:00	主持人开场 Opening Remarks by the Moderator	
10:00-10:30	具身智能的"神经中枢"：云边端协同架构的顶层设计与实践 The "Nerve Center" of Embodied AI: Top-Level Design and Implementation of Cloud-Edge-Device Collaborative Architectures	章畅海，百度云，制造行业解决方案总监 Zhang Changhai, Director of Manufacturing Industry Solutions, Baidu Cloud
10:30-11:00	AI赋能制造业数智化升级应用探讨 Exploring AI-Powered Digital and Intelligent Upgrading Applications in the Manufacturing Industry	李海鹏，科大讯飞国家智能语音创新中心，公共事务副总监 Li Haipeng, Deputy Director of Public Affairs, iFLYTEK National Intelligent Voice Innovation Center
11:00-11:30	具身机器人大小脑技术挑战与发展思路-灵境智源硅基大脑方案 Challenges and Development Approaches for Embodied Robotic Brain Technology: Mscape Silicon-Based Brain Solution	须海江，上海灵境智源科技有限公司，联合创始人/VP Xu Haijiang, Co-founder and Vice President, Shanghai Mscape Technology Co., Ltd.
11:30-12:00	5G+MEC网络如何为具身智能提供确定性连接 How 5G + MEC Networks Enable Deterministic Connectivity for Embodied AI	李冰，南凌科技股份有限公司，技术总监 Li Bing, Technical Director, NOVA Technology Company Limited
13:00-13:30	下午会议签到 Afternoon Registration	
13:30-14:00	具身智能巡检实战：数据算力驱动全场景全地形运维机器人的高效运维实践 Embodied AI Inspection Practices: Data and Computing Power Driving Efficient Operations in All-Scenario, All-Terrain Robotic Maintenance	赵亮，帝蛮神（上海）科技有限公司， iRIC 智能制造与机器人国际联创中心，技术总监 Zhao Liang, Technical Director, DiManShen(Shanghai)Technology Co., Ltd. IRIC Intelligent Manufacturing and Robotics International Joint Innovation Center
14:00-14:30	"冰点"算力：液冷边缘服务器赋能工业机器人集群的实践 "Freezing Point" Computing Power: Enabling Industrial Robot Clusters through Liquid-Cooled Edge Servers	韩雪兵，中科曙光，解决方案高级工程师 Han Xuebing, Senior Solution Engineer, Dawning Information Industry Co., Ltd.
14:30-15:00	"关节"的极限：机器人高功率密度执行器的热管理创新 Limits of "Joints": Innovations in Thermal Management for High Power Density Robotic Actuators	刘鹏，泰科电子，重点行业经理 Liu Peng, Key Account Manager, Tyco Electronics
15:00-15:30	云边端协同赋能工业智能体：罗克韦尔 PLEX&FT 工厂数字化解决方案实践 Empowering Industrial Intelligent Agents through Cloud-Edge-Device Collaboration: Practice of Rockwell PLEX & FT Digital Factory Solutions	王振华，罗克韦尔（中国）有限公司，软件经理 Wang Zhenhua, Software Manager, Rockwell Automation(China)Company Limited

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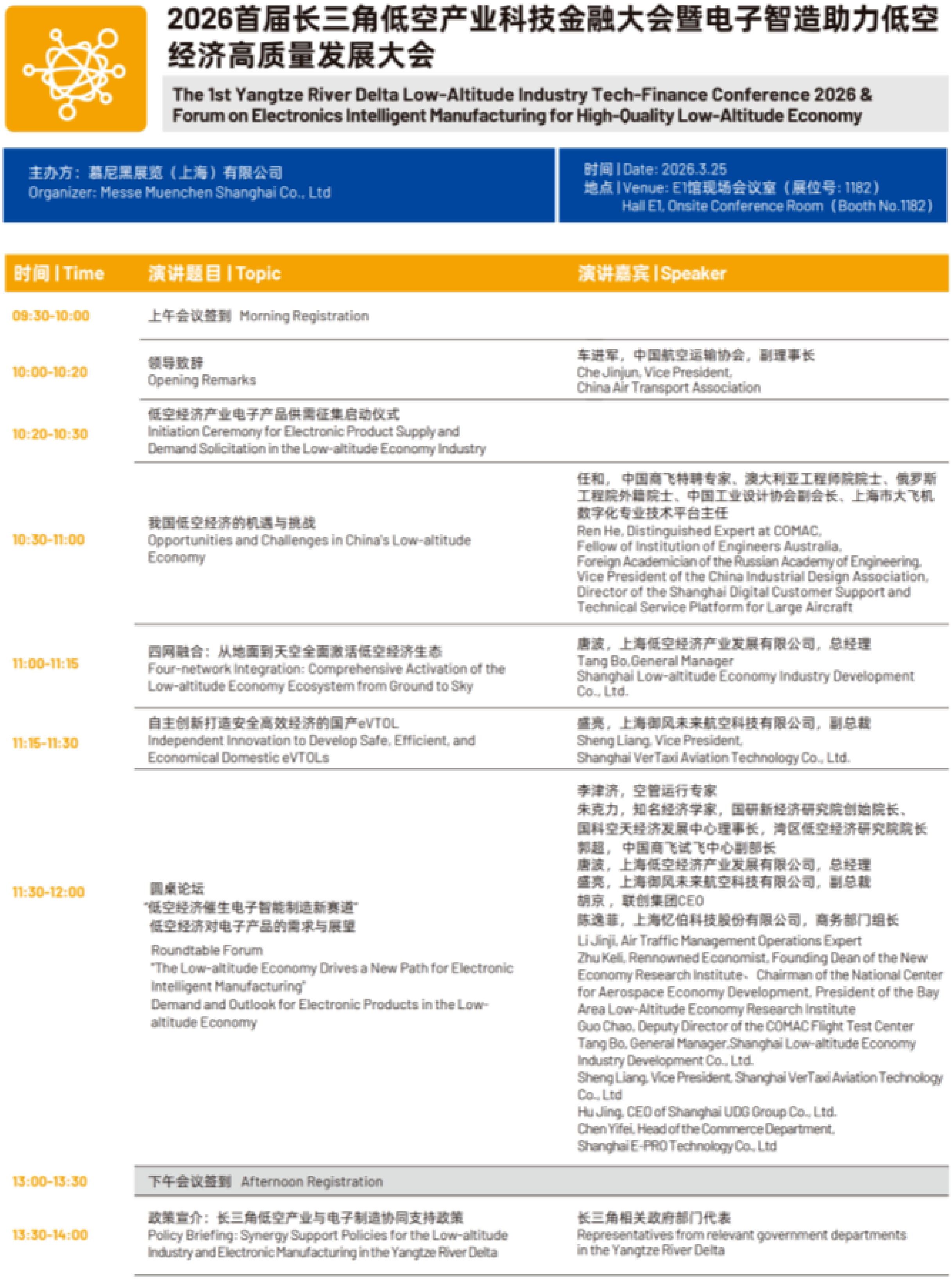


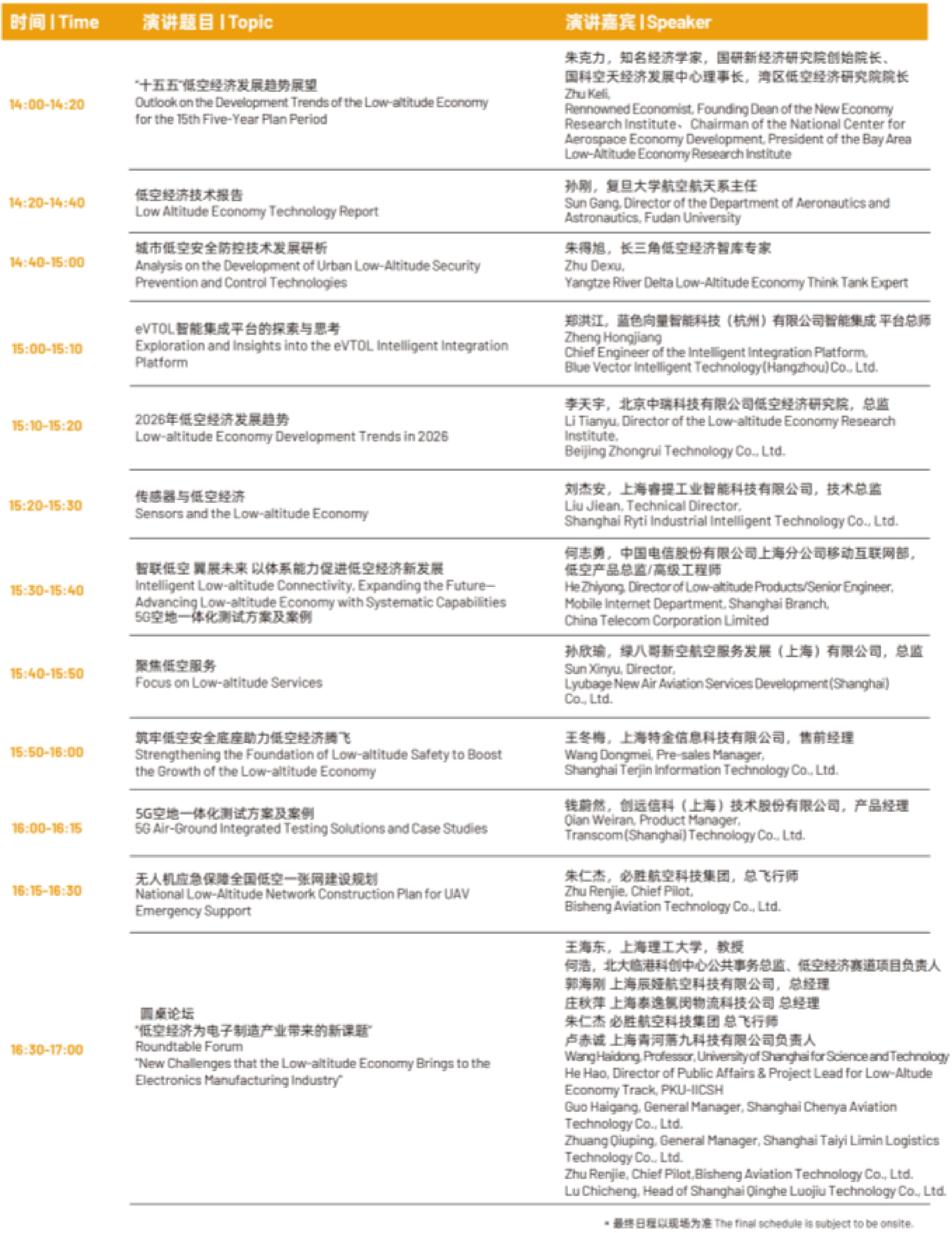
2026首届长三角低空产业科技金融大会暨电子智造助力低空经济高质量发展大会

The 1st Yangtze River Delta Low-Altitude Industry Tech-Finance Conference 2026 & Forum on Electronics Intelligent Manufacturing for High-Quality Low-Altitude Economy

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd

时间 | Date: 2026.3.25
地点 | Venue: E1馆现场会议室（展位号：1182）
Hall E1, Onsite Conference Room（Booth No.1182）

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:30-10:00	上午会议签到 Morning Registration	
10:00-10:20	领导致辞 Opening Remarks	车进军，中国航空运输协会，副理事长 Che Jinjun, Vice President, China Air Transport Association
10:20-10:30	低空经济产业电子产品供需征集启动仪式 Initiation Ceremony for Electronic Product Supply and Demand Solicitation in the Low-altitude Economy Industry	
10:30-11:00	我国低空经济的机遇与挑战 Opportunities and Challenges in China's Low-altitude Economy	任和，中国商飞特聘专家、澳大利亚工程师院院士、俄罗斯工程院外籍院士、中国工业设计协会副会长、上海市大飞机数字化专业技术平台主任 Ren He, Distinguished Expert at COMAC, Fellow of Institution of Engineers Australia, Foreign Academician of the Russian Academy of Engineering, Vice President of the China Industrial Design Association, Director of the Shanghai Digital Customer Support and Technical Service Platform for Large Aircraft
11:00-11:15	四网融合：从地面到天空全面激活低空经济生态 Four-network Integration: Comprehensive Activation of the Low-altitude Economy Ecosystem from Ground to Sky	唐波，上海低空经济产业发展有限公司，总经理 Tang Bo,General Manager Shanghai Low-altitude Economy Industry Development Co., Ltd.
11:15-11:30	自主创新打造安全高效经济的国产eVTOL Independent Innovation to Develop Safe, Efficient, and Economical Domestic eVTOLs	盛亮，上海御风未来航空科技有限公司，副总裁 Sheng Liang, Vice President, Shanghai VerTaxi Aviation Technology Co., Ltd.
11:30-12:00	圆桌论坛 “低空经济催生电子智能制造新赛道” 低空经济对电子产品的需求与展望 Roundtable Forum "The Low-altitude Economy Drives a New Path for Electronic Intelligent Manufacturing" Demand and Outlook for Electronic Products in the Low-altitude Economy	李津济，空管运行专家 朱克力，知名经济学家，国研新经济研究院创始院长、国科空天经济发展中心理事长，湾区低空经济研究院院长 郭超，中国商飞试飞中心副部长 唐波，上海低空经济产业发展有限公司，总经理 盛亮，上海御风未来航空科技有限公司，副总裁 胡京，联创集团CEO 陈逸菲，上海忆伯科技股份有限公司，商务部门组长 Li Jinji, Air Traffic Management Operations Expert Zhu Keli, Rennowned Economist, Founding Dean of the New Economy Research Institute、Chairman of the National Center for Aerospace Economy Development, President of the Bay Area Low-Altitude Economy Research Institute Guo Chao, Deputy Director of the COMAC Flight Test Center Tang Bo, General Manager,Shanghai Low-altitude Economy Industry Development Co., Ltd. Sheng Liang, Vice President, Shanghai VerTaxi Aviation Technology Co., Ltd Hu Jing, CEO of Shanghai UDG Group Co., Ltd. Chen Yifei, Head of the Commerce Department, Shanghai E-PRO Technology Co., Ltd
13:00-13:30	下午会议签到 Afternoon Registration	
13:30-14:00	政策宣介：长三角低空产业与电子制造协同支持政策 Policy Briefing: Synergy Support Policies for the Low-altitude Industry and Electronic Manufacturing in the Yangtze River Delta	长三角相关政府部门代表 Representatives from relevant government departments in the Yangtze River Delta



时间 I Time	演讲题目 I Topic	演讲嘉宾 I Speaker
14:00-14:20	"十五五"低空经济发展趋势展望 Outlook on the Development Trends of the Low-altitude Economy for the 15th Five-Year Plan Period	朱克力，知名经济学家，国研新经济研究院创始院长、国科空天经济发展中心理事长，湾区低空经济研究院院长 Zhu Keli, Rennowned Economist, Founding Dean of the New Economy Research Institute、Chairman of the National Center for Aerospace Economy Development, President of the Bay Area Low-Altitude Economy Research Institute
14:20-14:40	低空经济技术报告 Low Altitude Economy Technology Report	孙刚，复旦大学航空航天系主任 Sun Gang, Director of the Department of Aeronautics and Astronautics, Fudan University
14:40-15:00	城市低空安全防控技术发展研析 Analysis on the Development of Urban Low-Altitude Security Prevention and Control Technologies	朱得旭，长三角低空经济智库专家 Zhu Dexu, Yangtze River Delta Low-Altitude Economy Think Tank Expert
15:00-15:10	eVTOL智能集成平台的探索与思考 Exploration and Insights into the eVTOL Intelligent Integration Platform	郑洪江，蓝色向量智能科技（杭州）有限公司智能集成 平台总师 Zheng Hongjiang Chief Engineer of the Intelligent Integration Platform, Blue Vector Intelligent Technology(Hangzhou) Co., Ltd.
15:10-15:20	2026年低空经济发展趋势 Low-altitude Economy Development Trends in 2026	李天宇，北京中瑞科技有限公司低空经济研究院，总监 Li Tianyu, Director of the Low-altitude Economy Research Institute, Beijing Zhongrui Technology Co., Ltd.
15:20-15:30	传感器与低空经济 Sensors and the Low-altitude Economy	刘杰安，上海睿提工业智能科技有限公司，技术总监 Liu Jiean, Technical Director, Shanghai Ryti Industrial Intelligent Technology Co., Ltd.
15:30-15:40	智联低空 翼展未来 以体系能力促进低空经济新发展 Intelligent Low-altitude Connectivity, Expanding the Future—Advancing Low-altitude Economy with Systematic Capabilities 5G空地一体化测试方案及案例	何志勇，中国电信股份有限公司上海分公司移动互联网部，低空产品总监/高级工程师 He Zhiyong, Director of Low-altitude Products/Senior Engineer, Mobile Internet Department, Shanghai Branch, China Telecom Corporation Limited
15:40-15:50	聚焦低空服务 Focus on Low-altitude Services	孙欣瑜，绿八哥新空航空服务发展（上海）有限公司，总监 Sun Xinyu, Director, Lyubage New Air Aviation Services Development (Shanghai) Co., Ltd.
15:50-16:00	筑牢低空安全底座助力低空经济腾飞 Strengthening the Foundation of Low-altitude Safety to Boost the Growth of the Low-altitude Economy	王冬梅，上海特金信息科技有限公司，售前经理 Wang Dongmei, Pre-sales Manager, Shanghai Terjin Information Technology Co., Ltd.
16:00-16:15	5G空地一体化测试方案及案例 5G Air-Ground Integrated Testing Solutions and Case Studies	钱蔚然，创远信科（上海）技术股份有限公司，产品经理 Qian Weiran, Product Manager, Transcom (Shanghai) Technology Co., Ltd.
16:15-16:30	无人机应急保障全国低空一张网建设规划 National Low-Altitude Network Construction Plan for UAV Emergency Support	朱仁杰，必胜航空科技集团，总飞行师 Zhu Renjie, Chief Pilot, Bisheng Aviation Technology Co., Ltd.
16:30-17:00	圆桌论坛 "低空经济为电子制造产业带来的新课题" Roundtable Forum "New Challenges that the Low-altitude Economy Brings to the Electronics Manufacturing Industry"	王海东，上海理工大学，教授 何浩，北大临港科创中心公共事务总监、低空经济赛道项目负责人 郭海刚 上海辰娅航空科技有限公司，总经理 庄秋萍 上海泰逸氯闵物流科技公司 总经理 朱仁杰 必胜航空科技集团 总飞行师 卢赤诚 上海青河落九科技有限公司负责人 Wang Haidong, Professor, University of Shanghai for Science and Technology He Hao, Director of Public Affairs & Project Lead for Low-Altude Economy Track, PKU-IICSH Guo Haigang, General Manager, Shanghai Chenya Aviation Technology Co., Ltd. Zhuang Qiuping, General Manager, Shanghai Taiyi Limin Logistics Technology Co., Ltd. Zhu Renjie, Chief Pilot, Bisheng Aviation Technology Co., Ltd. Lu Chicheng, Head of Shanghai Qinghe Luojiu Technology Co., Ltd.

• 最终日程以现场为准 The final schedule is subject to be onsite.

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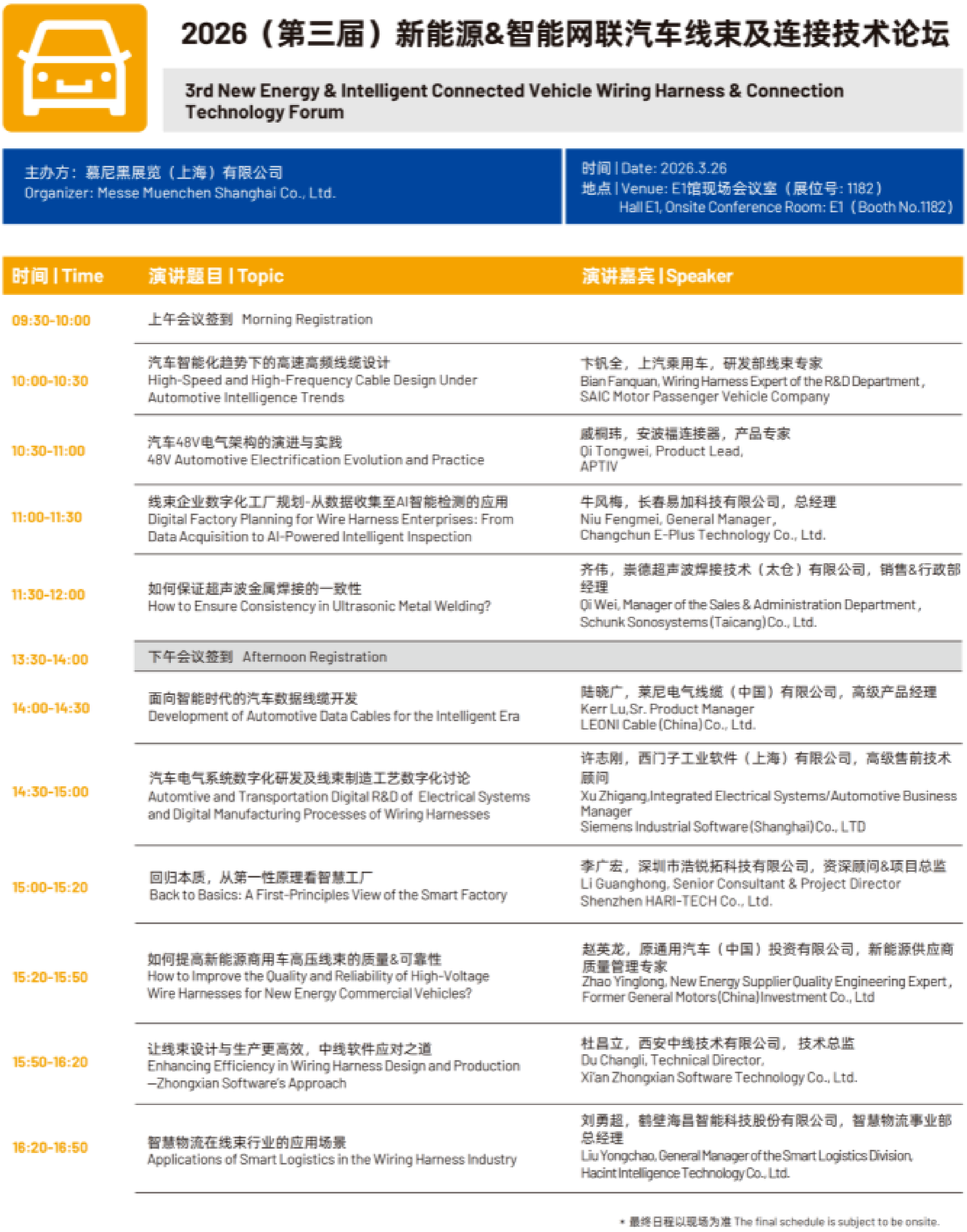

2026（第三届）新能源&智能网联汽车线束及连接技术论坛

3rd New Energy & Intelligent Connected Vehicle Wiring Harness & Connection Technology Forum

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.26
地点 | Venue: E1馆现场会议室（展位号：1182）
Hall E1, Onsite Conference Room: E1（Booth No.1182）

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:30-10:00	上午会议签到 Morning Registration	
10:00-10:30	汽车智能化趋势下的高速高频线缆设计 High-Speed and High-Frequency Cable Design Under Automotive Intelligence Trends	卞钒全，上汽乘用车，研发部线束专家 Bian Fanquan, Wiring Harness Expert of the R&D Department, SAIC Motor Passenger Vehicle Company
10:30-11:00	汽车48V电气架构的演进与实践 48V Automotive Electrification Evolution and Practice	戚桐玮，安波福连接器，产品专家 Qi Tongwei, Product Lead, APTIV
11:00-11:30	线束企业数字化工厂规划-从数据收集至AI智能检测的应用 Digital Factory Planning for Wire Harness Enterprises: From Data Acquisition to AI-Powered Intelligent Inspection	牛凤梅，长春易加科技有限公司，总经理 Niu Fengmei, General Manager, Changchun E-Plus Technology Co., Ltd.
11:30-12:00	如何保证超声波金属焊接的一致性 How to Ensure Consistency in Ultrasonic Metal Welding?	齐伟，崇德超声波焊接技术（太仓）有限公司，销售&行政部经理 Qi Wei, Manager of the Sales & Administration Department, Schunk Sonosystems (Taicang) Co., Ltd.
13:30-14:00	下午会议签到 Afternoon Registration	
14:00-14:30	面向智能时代的汽车数据线缆开发 Development of Automotive Data Cables for the Intelligent Era	陆晓广，莱尼电气线缆（中国）有限公司，高级产品经理 Kerr Lu,Sr. Product Manager LEONI Cable (China) Co., Ltd.
14:30-15:00	汽车电气系统数字化研发及线束制造工艺数字化讨论 Automtive and Transportation Digital R&D of Electrical Systems and Digital Manufacturing Processes of Wiring Harnesses	许志刚，西门子工业软件（上海）有限公司，高级售前技术顾问 Xu Zhigang,Integrated Electrical Systems/Automotive Business Manager Siemens Industrial Software (Shanghai) Co., LTD
15:00-15:20	回归本质，从第一性原理看智慧工厂 Back to Basics: A First-Principles View of the Smart Factory	李广宏，深圳市浩锐拓科技有限公司，资深顾问&项目总监 Li Guanghong, Senior Consultant & Project Director Shenzhen HARI-TECH Co., Ltd.
15:20-15:50	如何提高新能源商用车高压线束的质量&可靠性 How to Improve the Quality and Reliability of High-Voltage Wire Harnesses for New Energy Commercial Vehicles?	赵英龙，原通用汽车（中国）投资有限公司，新能源供应商质量管理专家 Zhao Yinglong, New Energy Supplier Quality Engineering Expert, Former General Motors (China) Investment Co., Ltd
15:50-16:20	让线束设计与生产更高效，中线软件应对之道 Enhancing Efficiency in Wiring Harness Design and Production –Zhongxian Software's Approach	杜昌立，西安中线技术有限公司，技术总监 Du Changli, Technical Director, Xi'an Zhongxian Software Technology Co., Ltd.
16:20-16:50	智慧物流在线束行业的应用场景 Applications of Smart Logistics in the Wiring Harness Industry	刘勇超，鹤壁海昌智能科技股份有限公司，智慧物流事业部总经理 Liu Yongchao, General Manager of the Smart Logistics Division, Hacint Intelligence Technology Co., Ltd.

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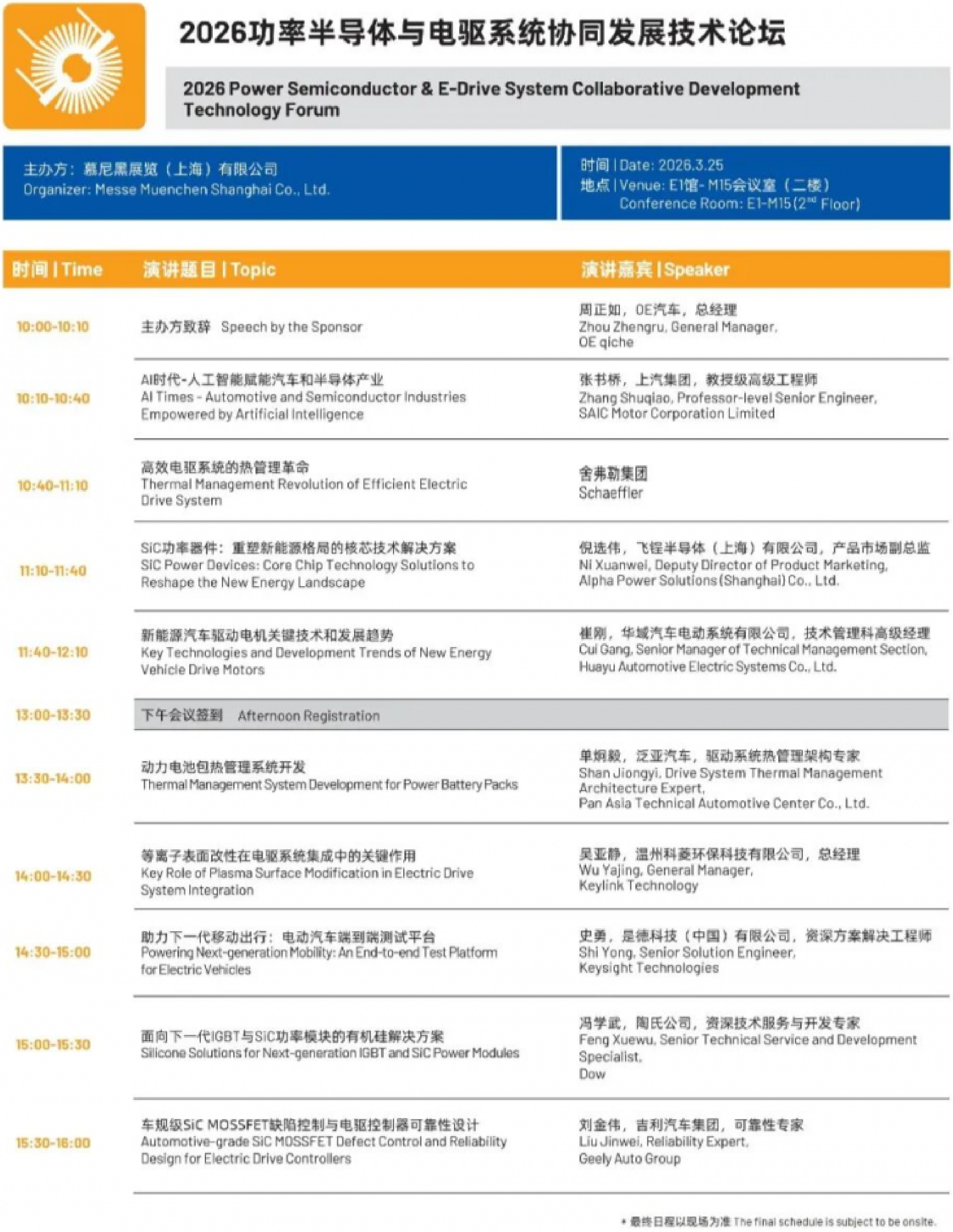

2026功率半导体与电驱系统协同发展技术论坛

2026 Power Semiconductor & E-Drive System Collaborative Development Technology Forum

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.25
地点 | Venue: E1馆- M15会议室（二楼）
Conference Room: E1-M15 (2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
10:00-10:10	主办方致辞 Speech by the Sponsor	周正如，OE汽车，总经理 Zhou Zhengru, General Manager, OE qiche
10:10-10:40	AI时代-人工智能赋能汽车和半导体产业 AI Times - Automotive and Semiconductor Industries Empowered by Artificial Intelligence	张书桥，上汽集团，教授级高级工程师 Zhang Shuqiao, Professor-level Senior Engineer, SAIC Motor Corporation Limited
10:40-11:10	高效电驱系统的热管理革命 Thermal Management Revolution of Efficient Electric Drive System	舍弗勒集团 Schaeffler
11:10-11:40	SiC功率器件：重塑新能源格局的核芯技术解决方案 SiC Power Devices: Core Chip Technology Solutions to Reshape the New Energy Landscape	倪选伟，飞锃半导体（上海）有限公司，产品市场副总监 Ni Xuanwei, Deputy Director of Product Marketing, Alpha Power Solutions (Shanghai) Co., Ltd.
11:40-12:10	新能源汽车驱动电机关键技术和发展趋势 Key Technologies and Development Trends of New Energy Vehicle Drive Motors	崔刚，华域汽车电动系统有限公司，技术管理科高级经理 Cui Gang, Senior Manager of Technical Management Section, Huayu Automotive Electric Systems Co., Ltd.
13:00-13:30	下午会议签到 Afternoon Registration	
13:30-14:00	动力电池包热管理系统开发 Thermal Management System Development for Power Battery Packs	单炯毅，泛亚汽车，驱动系统热管理架构专家 Shan Jiongyi, Drive System Thermal Management Architecture Expert, Pan Asia Technical Automotive Center Co., Ltd.
14:00-14:30	等离子表面改性在电驱系统集成中的关键作用 Key Role of Plasma Surface Modification in Electric Drive System Integration	吴亚静，温州科菱环保科技有限公司，总经理 Wu Yajing, General Manager, Keylink Technology
14:30-15:00	助力下一代移动出行：电动汽车端到端测试平台 Powering Next-generation Mobility: An End-to-end Test Platform for Electric Vehicles	史勇，是德科技（中国）有限公司，资深方案解决工程师 Shi Yong, Senior Solution Engineer, Keysight Technologies
15:00-15:30	面向下一代IGBT与SiC功率模块的有机硅解决方案 Silicone Solutions for Next-generation IGBT and SiC Power Modules	冯学武，陶氏公司，资深技术服务与开发专家 Feng Xuewu, Senior Technical Service and Development Specialist, Dow
15:30-16:00	车规级SiC MOSSFET缺陷控制与电驱控制器可靠性设计 Automotive-grade SiC MOSSFET Defect Control and Reliability Design for Electric Drive Controllers	刘金伟，吉利汽车集团，可靠性专家 Liu Jinwei, Reliability Expert, Geely Auto Group

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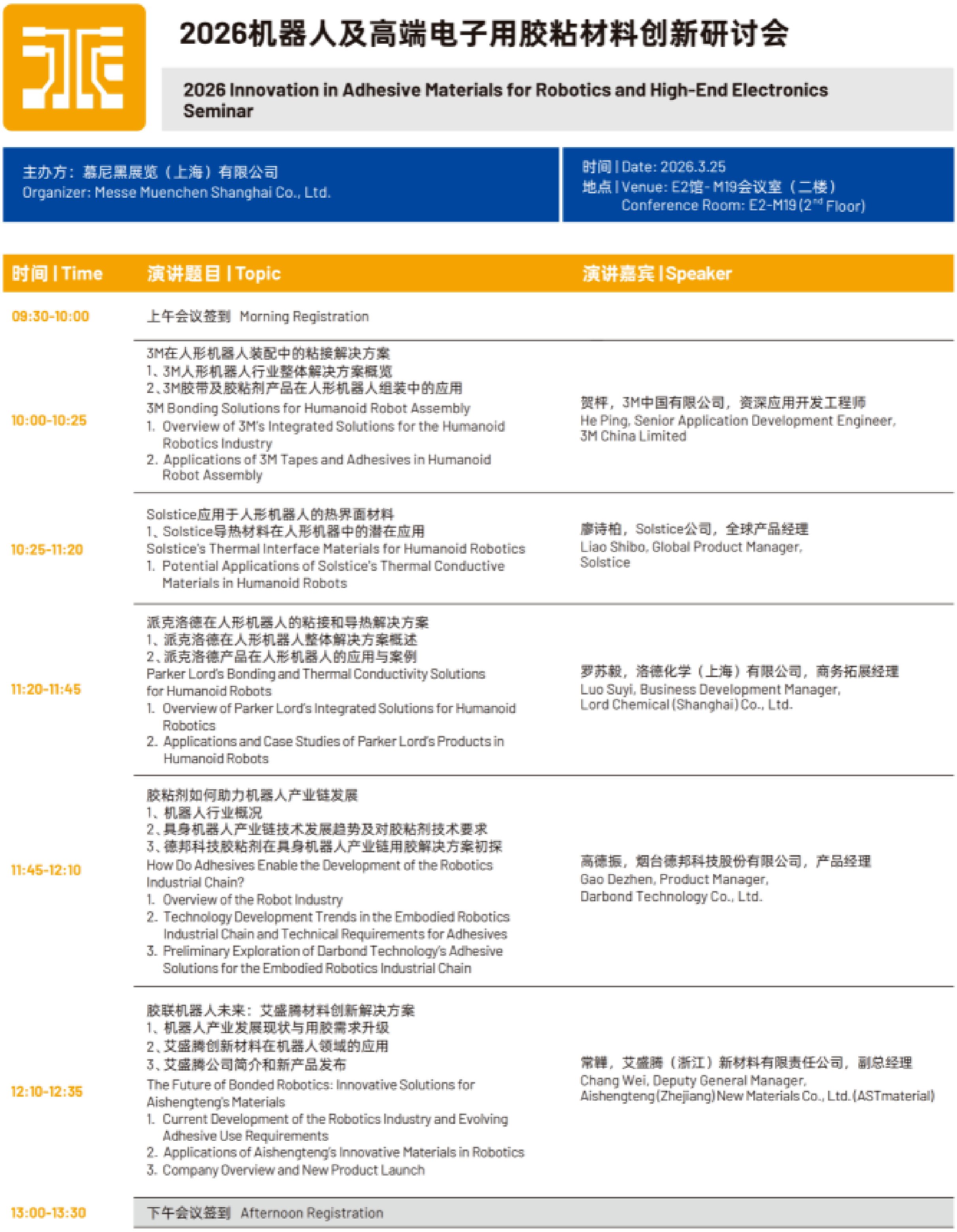


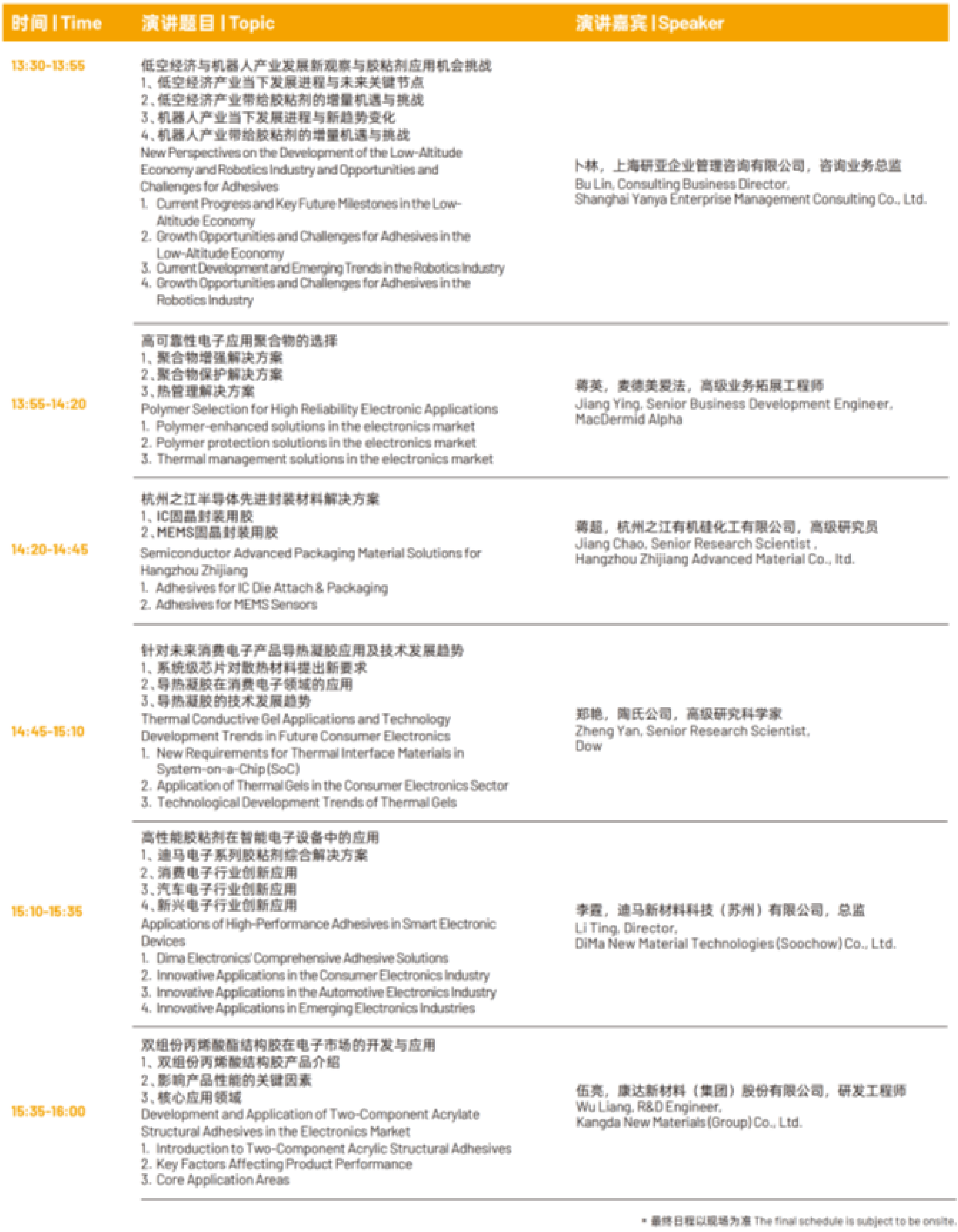
2026机器人及高端电子用胶粘材料创新研讨会

2026 Innovation in Adhesive Materials for Robotics and High-End Electronics Seminar

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.25
地点 | Venue: E2馆 - M19会议室（二楼）
Conference Room: E2-M19 (2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:30-10:00	上午会议签到 Morning Registration	
10:00-10:25	3M在人形机器人装配中的粘接解决方案 1、3M人形机器人行业整体解决方案概览 2、3M胶带及胶粘剂产品在人形机器人组装中的应用 3M Bonding Solutions for Humanoid Robot Assembly 1. Overview of 3M's Integrated Solutions for the Humanoid Robotics Industry 2. Applications of 3M Tapes and Adhesives in Humanoid Robot Assembly	贺枰，3M中国有限公司，资深应用开发工程师 He Ping, Senior Application Development Engineer, 3M China Limited
10:25-11:20	Solstice应用于人形机器人的热界面材料 1、Solstice导热材料在人形机器中的潜在应用 Solstice's Thermal Interface Materials for Humanoid Robotics 1. Potential Applications of Solstice's Thermal Conductive Materials in Humanoid Robots	廖诗柏，Solstice公司，全球产品经理 Liao Shibo, Global Product Manager, Solstice
11:20-11:45	派克洛德在人形机器人的粘接和导热解决方案 1、派克洛德在人形机器人整体解决方案概述 2、派克洛德产品在人形机器人的应用与案例 Parker Lord's Bonding and Thermal Conductivity Solutions for Humanoid Robots 1. Overview of Parker Lord's Integrated Solutions for Humanoid Robotics 2. Applications and Case Studies of Parker Lord's Products in Humanoid Robots	罗苏毅，洛德化学（上海）有限公司，商务拓展经理 Luo Suyi, Business Development Manager, Lord Chemical (Shanghai) Co., Ltd.
11:45-12:10	胶粘剂如何助力机器人产业链发展 1、机器人行业概况 2、具身机器人产业链技术发展趋势及对胶粘剂技术要求 3、德邦科技胶粘剂在具身机器人产业链用胶解决方案初探 How Do Adhesives Enable the Development of the Robotics Industrial Chain? 1. Overview of the Robot Industry 2. Technology Development Trends in the Embodied Robotics Industrial Chain and Technical Requirements for Adhesives 3. Preliminary Exploration of Darbond Technology's Adhesive Solutions for the Embodied Robotics Industrial Chain	高德振，烟台德邦科技股份有限公司，产品经理 Gao Dezhen, Product Manager, Darbond Technology Co., Ltd.
12:10-12:35	胶联机器人未来：艾盛腾材料创新解决方案 1、机器人产业发展现状与用胶需求升级 2、艾盛腾创新材料在机器人领域的应用 3、艾盛腾公司简介和新产品发布 The Future of Bonded Robotics: Innovative Solutions for Aishengteng's Materials 1. Current Development of the Robotics Industry and Evolving Adhesive Use Requirements 2. Applications of Aishengteng's Innovative Materials in Robotics 3. Company Overview and New Product Launch	常韡，艾盛腾（浙江）新材料有限责任公司，副总经理 Chang Wei, Deputy General Manager, Aishengteng (Zhejiang) New Materials Co., Ltd. (ASTmaterial)
13:00-13:30	下午会议签到 Afternoon Registration	



时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
13:30-13:55	低空经济与机器人产业发展新观察与胶粘剂应用机会挑战 1、低空经济产业当下发展进程与未来关键节点 2、低空经济产业带给胶粘剂的增量机遇与挑战 3、机器人产业当下发展进程与新趋势变化 4、机器人产业带给胶粘剂的增量机遇与挑战 New Perspectives on the Development of the Low-Altitude Economy and Robotics Industry and Opportunities and Challenges for Adhesives 1. Current Progress and Key Future Milestones in the Low-Altitude Economy 2. Growth Opportunities and Challenges for Adhesives in the Low-Altitude Economy 3. Current Development and Emerging Trends in the Robotics Industry 4. Growth Opportunities and Challenges for Adhesives in the Robotics Industry	卜林，上海研亚企业管理咨询有限公司，咨询业务总监 Bu Lin, Consulting Business Director, Shanghai Yanya Enterprise Management Consulting Co., Ltd.
13:55-14:20	高可靠性电子应用聚合物的选择 1、聚合物增强解决方案 2、聚合物保护解决方案 3、热管理解决方案 Polymer Selection for High Reliability Electronic Applications 1. Polymer-enhanced solutions in the electronics market 2. Polymer protection solutions in the electronics market 3. Thermal management solutions in the electronics market	蒋英，麦德美爱法，高级业务拓展工程师 Jiang Ying, Senior Business Development Engineer, MacDermid Alpha
14:20-14:45	杭州之江半导体先进封装材料解决方案 1、IC固晶封装用胶 2、MEMS固晶封装用胶 Semiconductor Advanced Packaging Material Solutions for Hangzhou Zhijiang 1. Adhesives for IC Die Attach & Packaging 2. Adhesives for MEMS Sensors	蒋超，杭州之江有机硅化工有限公司，高级研究员 Jiang Chao, Senior Research Scientist , Hangzhou Zhijiang Advanced Material Co., ltd.
14:45-15:10	针对未来消费电子产品导热凝胶应用及技术发展趋势 1、系统级芯片对散热材料提出新要求 2、导热凝胶在消费电子领域的应用 3、导热凝胶的技术发展趋势 Thermal Conductive Gel Applications and Technology Development Trends in Future Consumer Electronics 1. New Requirements for Thermal Interface Materials in System-on-a-Chip (SoC) 2. Application of Thermal Gels in the Consumer Electronics Sector 3. Technological Development Trends of Thermal Gels	郑艳，陶氏公司，高级研究科学家 Zheng Yan, Senior Research Scientist, Dow
15:10-15:35	高性能胶粘剂在智能电子设备中的应用 1、迪马电子系列胶粘剂综合解决方案 2、消费电子行业创新应用 3、汽车电子行业创新应用 4、新兴电子行业创新应用 Applications of High-Performance Adhesives in Smart Electronic Devices 1. Dima Electronics' Comprehensive Adhesive Solutions 2. Innovative Applications in the Consumer Electronics Industry 3. Innovative Applications in the Automotive Electronics Industry 4. Innovative Applications in Emerging Electronics Industries	李霆，迪马新材料科技（苏州）有限公司，总监 Li Ting, Director, DiMa New Material Technologies (Soochow) Co., Ltd.
15:35-16:00	双组份丙烯酸酯结构胶在电子市场的开发与应用 1、双组份丙烯酸结构胶产品介绍 2、影响产品性能的关键因素 3、核心应用领域 Development and Application of Two-Component Acrylate Structural Adhesives in the Electronics Market 1. Introduction to Two-Component Acrylic Structural Adhesives 2. Key Factors Affecting Product Performance 3. Core Application Areas	伍亮，康达新材料（集团）股份有限公司，研发工程师 Wu Liang, R&D Engineer, Kangda New Materials (Group) Co., Ltd.

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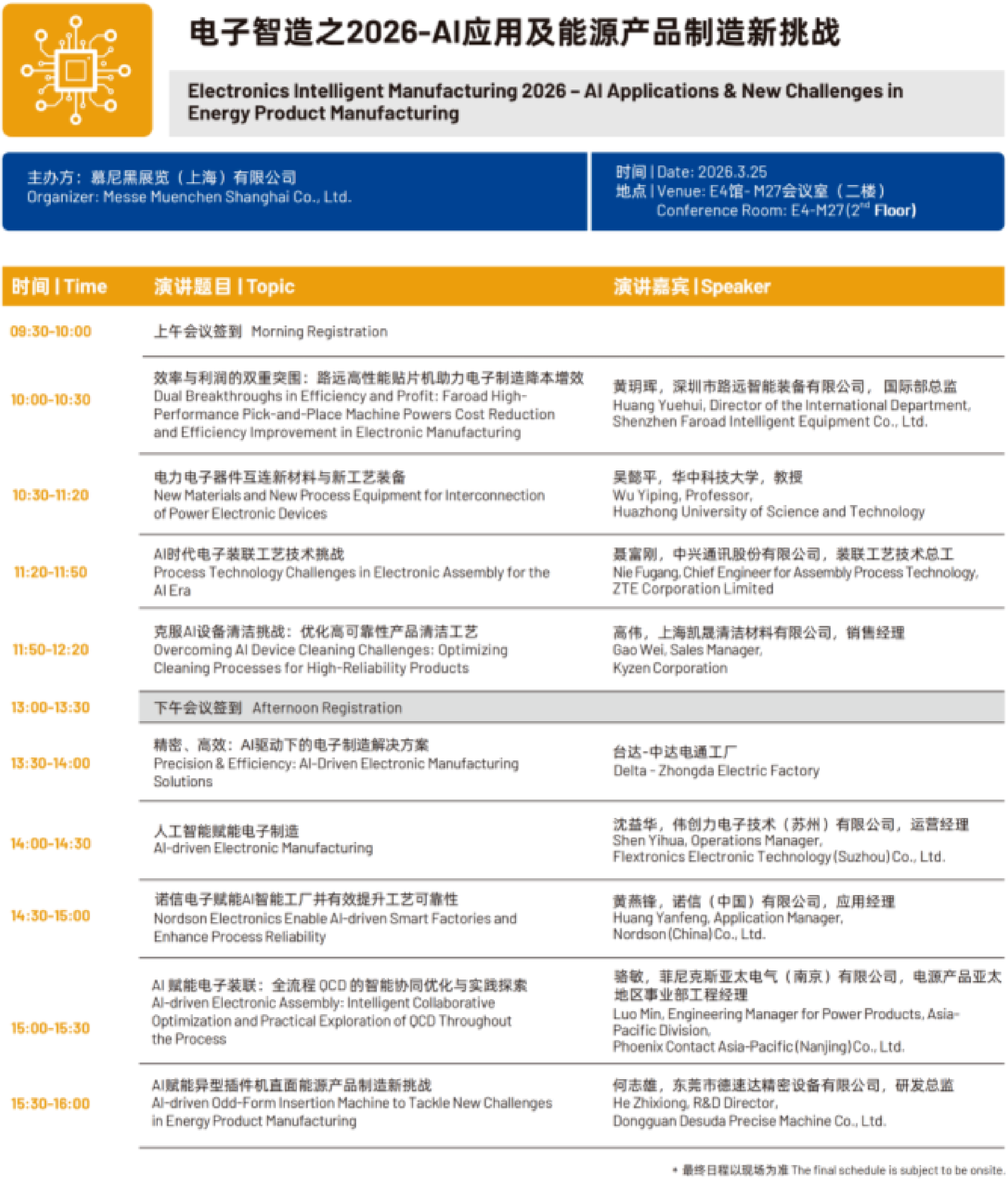

电子智造之2026-AI应用及能源产品制造新挑战

Electronics Intelligent Manufacturing 2026 – AI Applications & New Challenges in Energy Product Manufacturing

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.25
地点 | Venue: E4馆- M27会议室（二楼）
Conference Room: E4-M27(2^{nd} Floor)

时间 I Time	演讲题目 I Topic	演讲嘉宾 I Speaker
09:30-10:00	上午会议签到 Morning Registration	
10:00-10:30	效率与利润的双重突围：路远高性能贴片机助力电子制造降本增效 Dual Breakthroughs in Efficiency and Profit: Faroad High-Performance Pick-and-Place Machine Powers Cost Reduction and Efficiency Improvement in Electronic Manufacturing	黄玥珲，深圳市路远智能装备有限公司，国际部总监 Huang Yuehui, Director of the International Department, Shenzhen Faroad Intelligent Equipment Co., Ltd.
10:30-11:20	电力电子器件互连新材料与新工艺装备 New Materials and New Process Equipment for Interconnection of Power Electronic Devices	吴懿平，华中科技大学，教授 Wu Yiping, Professor, Huazhong University of Science and Technology
11:20-11:50	AI时代电子装联工艺技术挑战 Process Technology Challenges in Electronic Assembly for the AI Era	聂富刚，中兴通讯股份有限公司，装联工艺技术总工 Nie Fugang, Chief Engineer for Assembly Process Technology, ZTE Corporation Limited
11:50-12:20	克服AI设备清洁挑战：优化高可靠性产品清洁工艺 Overcoming AI Device Cleaning Challenges: Optimizing Cleaning Processes for High-Reliability Products	高伟，上海凯晟清洁材料有限公司，销售经理 Gao Wei, Sales Manager, Kyzen Corporation
13:00-13:30	下午会议签到 Afternoon Registration	
13:30-14:00	精密、高效：AI驱动下的电子制造解决方案 Precision & Efficiency: AI-Driven Electronic Manufacturing Solutions	台达-中达电通工厂 Delta - Zhongda Electric Factory
14:00-14:30	人工智能赋能电子制造 AI-driven Electronic Manufacturing	沈益华，伟创力电子技术（苏州）有限公司，运营经理 Shen Yihua, Operations Manager, Flextronics Electronic Technology (Suzhou) Co., Ltd.
14:30-15:00	诺信电子赋能AI智能工厂并有效提升工艺可靠性 Nordson Electronics Enable AI-driven Smart Factories and Enhance Process Reliability	黄燕锋，诺信（中国）有限公司，应用经理 Huang Yanfeng, Application Manager, Nordson (China) Co., Ltd.
15:00-15:30	AI 赋能电子装联：全流程 QCD 的智能协同优化与实践探索 AI-driven Electronic Assembly: Intelligent Collaborative Optimization and Practical Exploration of QCD Throughout the Process	骆敏，菲尼克斯亚太电气（南京）有限公司，电源产品亚太地区事业部工程经理 Luo Min, Engineering Manager for Power Products, Asia-Pacific Division, Phoenix Contact Asia-Pacific (Nanjing) Co., Ltd.
15:30-16:00	AI赋能异型插件机直面能源产品制造新挑战 AI-driven Odd-Form Insertion Machine to Tackle New Challenges in Energy Product Manufacturing	何志雄，东莞市德速达精密设备有限公司，研发总监 He Zhixiong, R&D Director, Dongguan Desuda Precise Machine Co., Ltd.

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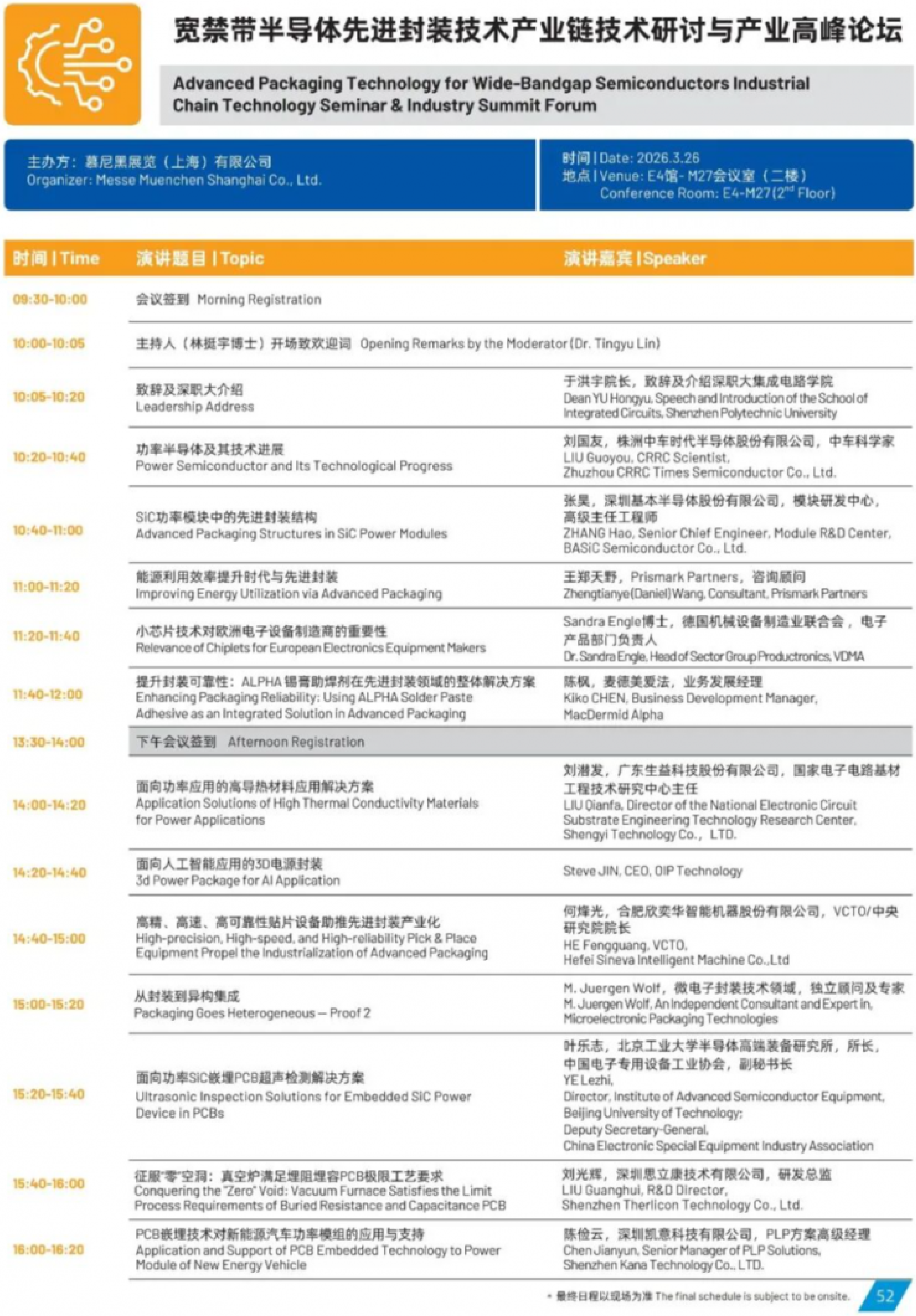

宽禁带半导体先进封装技术产业链技术研讨与产业高峰论坛

Advanced Packaging Technology for Wide-Bandgap Semiconductors Industrial Chain Technology Seminar & Industry Summit Forum

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.26
地点 | Venue: E4馆- M27会议室（二楼）
Conference Room: E4-M27 (2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:30-10:00	会议签到 Morning Registration	
10:00-10:05	主持人（林挺宇博士）开场致欢迎词 Opening Remarks by the Moderator (Dr. Tingyu Lin)	
10:05-10:20	致辞及深职大介绍 Leadership Address	于洪宇院长，致辞及介绍深职大集成电路学院 Dean YU Hongyu, Speech and Introduction of the School of Integrated Circuits, Shenzhen Polytechnic University
10:20-10:40	功率半导体及其技术进展 Power Semiconductor and Its Technological Progress	刘国友，株洲中车时代半导体股份有限公司，中车科学家 LIU Guoyou, CRRC Scientist, Zhuzhou CRRC Times Semiconductor Co., Ltd.
10:40-11:00	SiC功率模块中的先进封装结构 Advanced Packaging Structures in SiC Power Modules	张昊，深圳基本半导体股份有限公司，模块研发中心，高级主任工程师 ZHANG Hao, Senior Chief Engineer, Module R&D Center, BASiC Semiconductor Co., Ltd.
11:00-11:20	能源利用效率提升时代与先进封装 Improving Energy Utilization via Advanced Packaging	王郑天野，Prismark Partners，咨询顾问 Zhengtianye (Daniel) Wang, Consultant, Prismark Partners
11:20-11:40	小芯片技术对欧洲电子设备制造商的重要性 Relevance of Chiplets for European Electronics Equipment Makers	Sandra Engle博士，德国机械设备制造业联合会，电子产品部门负责人 Dr. Sandra Engle, Head of Sector Group Productronics, VDMA
11:40-12:00	提升封装可靠性：ALPHA 锡膏助焊剂在先进封装领域的整体解决方案 Enhancing Packaging Reliability: Using ALPHA Solder Paste Adhesive as an Integrated Solution in Advanced Packaging	陈枫，麦德美爱法，业务发展经理 Kiko CHEN, Business Development Manager, MacDermid Alpha
13:30-14:00	下午会议签到 Afternoon Registration	
14:00-14:20	面向功率应用的高导热材料应用解决方案 Application Solutions of High Thermal Conductivity Materials for Power Applications	刘潜发，广东生益科技股份有限公司，国家电子电路基材工程技术研究中心主任 LIU Qianfa, Director of the National Electronic Circuit Substrate Engineering Technology Research Center, Shengyi Technology Co.，LTD.
14:20-14:40	面向人工智能应用的3D电源封装 3d Power Package for AI Application	Steve JIN, CEO, OIP Technology
14:40-15:00	高精、高速、高可靠性贴片设备助推先进封装产业化 High-precision, High-speed, and High-reliability Pick & Place Equipment Propel the Industrialization of Advanced Packaging	何烽光，合肥欣奕华智能机器股份有限公司，VCTO/中央研究院院长 HE Fengguang, VCTO, Hefei Sineva Intelligent Machine Co.,Ltd
15:00-15:20	从封装到异构集成 Packaging Goes Heterogeneous — Proof 2	M. Juergen Wolf，微电子封装技术领域，独立顾问及专家 M. Juergen Wolf, An Independent Consultant and Expert in, Microelectronic Packaging Technologies
15:20-15:40	面向功率SiC嵌埋PCB超声检测解决方案 Ultrasonic Inspection Solutions for Embedded SiC Power Device in PCBs	叶乐志，北京工业大学半导体高端装备研究所，所长，中国电子专用设备工业协会，副秘书长 YE Lezhi, Director, Institute of Advanced Semiconductor Equipment, Beijing University of Technology; Deputy Secretary-General, China Electronic Special Equipment Industry Association
15:40-16:00	征服"零"空洞：真空炉满足埋阻埋容PCB极限工艺要求 Conquering the "Zero" Void: Vacuum Furnace Satisfies the Limit Process Requirements of Buried Resistance and Capacitance PCB	刘光辉，深圳思立康技术有限公司，研发总监 LIU Guanghui, R&D Director, Shenzhen Therlicon Technology Co., Ltd.
16:00-16:20	PCB嵌埋技术对新能源汽车功率模组的应用与支持 Application and Support of PCB Embedded Technology to Power Module of New Energy Vehicle	陈俭云，深圳凯意科技有限公司，PLP方案高级经理 Chen Jianyun, Senior Manager of PLP Solutions, Shenzhen Kana Technology Co., LTD.

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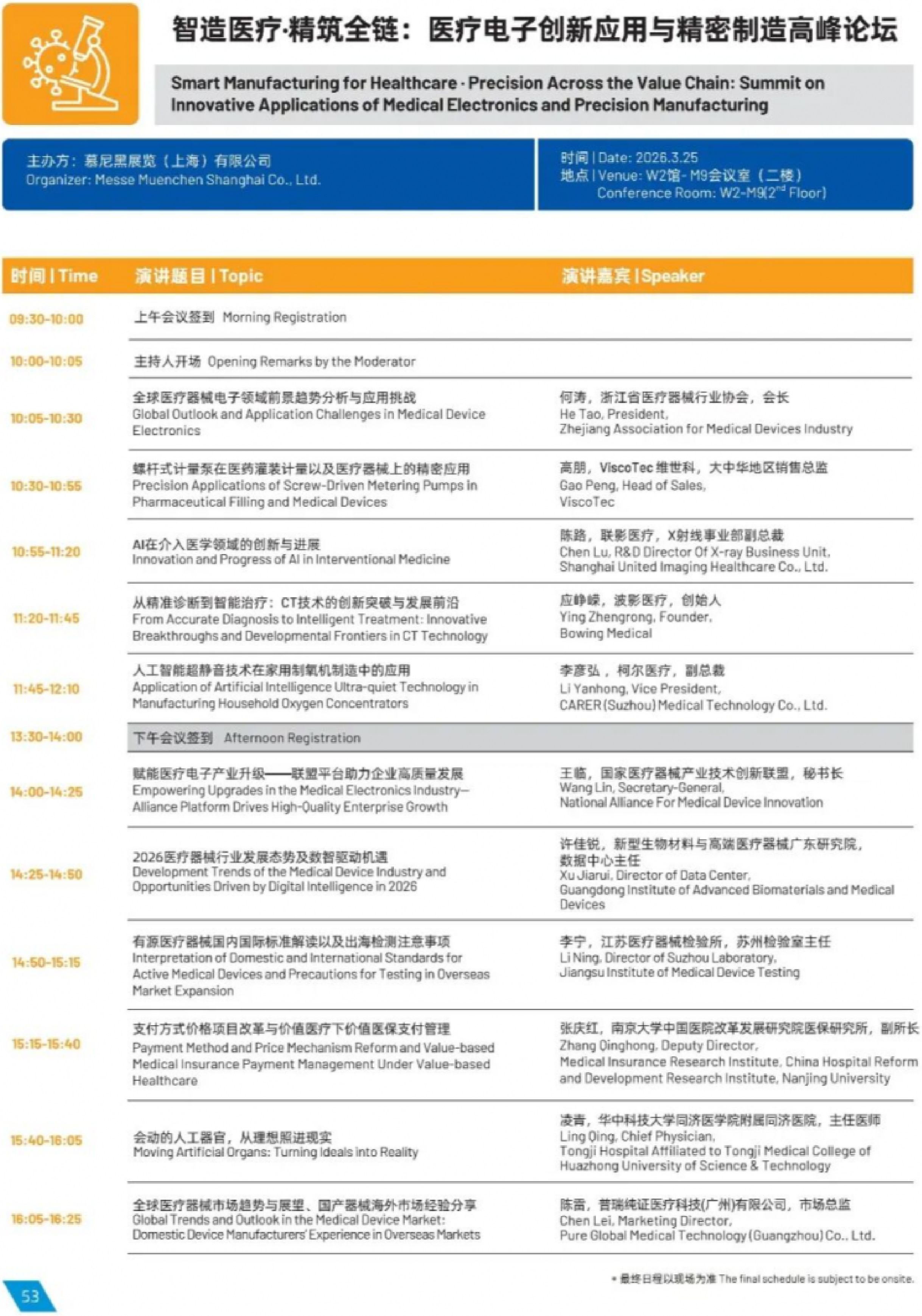

智造医疗·精筑全链：医疗电子创新应用与精密制造高峰论坛

Smart Manufacturing for Healthcare · Precision Across the Value Chain: Summit on Innovative Applications of Medical Electronics and Precision Manufacturing

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.25
地点 | Venue: W2馆 - M9会议室（二楼）
Conference Room: W2-M9(2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:30-10:00	上午会议签到 Morning Registration	
10:00-10:05	主持人开场 Opening Remarks by the Moderator	
10:05-10:30	全球医疗器械电子领域前景趋势分析与应用挑战 Global Outlook and Application Challenges in Medical Device Electronics	何涛，浙江省医疗器械行业协会，会长 He Tao, President, Zhejiang Association for Medical Devices Industry
10:30-10:55	螺杆式计量泵在医药灌装计量以及医疗器械上的精密应用 Precision Applications of Screw-Driven Metering Pumps in Pharmaceutical Filling and Medical Devices	高朋，ViscoTec 维世科，大中华地区销售总监 Gao Peng, Head of Sales, ViscoTec
10:55-11:20	AI在介入医学领域的创新与进展 Innovation and Progress of AI in Interventional Medicine	陈路，联影医疗，X射线事业部副总裁 Chen Lu, R&D Director Of X-ray Business Unit, Shanghai United Imaging Healthcare Co., Ltd.
11:20-11:45	从精准诊断到智能治疗：CT技术的创新突破与发展前沿 From Accurate Diagnosis to Intelligent Treatment: Innovative Breakthroughs and Developmental Frontiers in CT Technology	应峥嵘，波影医疗，创始人 Ying Zhengrong, Founder, Bowing Medical
11:45-12:10	人工智能超静音技术在家用制氧机制造中的应用 Application of Artificial Intelligence Ultra-quiet Technology in Manufacturing Household Oxygen Concentrators	李彦弘，柯尔医疗，副总裁 Li Yanhong, Vice President, CARER (Suzhou) Medical Technology Co., Ltd.
13:30-14:00	下午会议签到 Afternoon Registration	
14:00-14:25	赋能医疗电子产业升级——联盟平台助力企业高质量发展 Empowering Upgrades in the Medical Electronics Industry—Alliance Platform Drives High-Quality Enterprise Growth	王临，国家医疗器械产业技术创新联盟，秘书长 Wang Lin, Secretary-General, National Alliance For Medical Device Innovation
14:25-14:50	2026医疗器械行业发展态势及数智驱动机遇 Development Trends of the Medical Device Industry and Opportunities Driven by Digital Intelligence in 2026	许佳锐，新型生物材料与高端医疗器械广东研究院，数据中心主任 Xu Jiarui, Director of Data Center, Guangdong Institute of Advanced Biomaterials and Medical Devices
14:50-15:15	有源医疗器械国内国际标准解读以及出海检测注意事项 Interpretation of Domestic and International Standards for Active Medical Devices and Precautions for Testing in Overseas Market Expansion	李宁，江苏医疗器械检验所，苏州检验室主任 Li Ning, Director of Suzhou Laboratory, Jiangsu Institute of Medical Device Testing
15:15-15:40	支付方式价格项目改革与价值医疗下价值医保支付管理 Payment Method and Price Mechanism Reform and Value-based Medical Insurance Payment Management Under Value-based Healthcare	张庆红，南京大学中国医院改革发展研究院医保研究所，副所长 Zhang Qinghong, Deputy Director, Medical Insurance Research Institute, China Hospital Reform and Development Research Institute, Nanjing University
15:40-16:05	会动的人工器官，从理想照进现实 Moving Artificial Organs: Turning Ideals into Reality	凌青，华中科技大学同济医学院附属同济医院，主任医师 Ling Qing, Chief Physician, Tongji Hospital Affiliated to Tongji Medical College of Huazhong University of Science & Technology
16:05-16:25	全球医疗器械市场趋势与展望、国产器械海外市场经验分享 Global Trends and Outlook in the Medical Device Market: Domestic Device Manufacturers' Experience in Overseas Markets	陈雷，普瑞纯证医疗科技(广州)有限公司，市场总监 Chen Lei, Marketing Director, Pure Global Medical Technology (Guangzhou) Co., Ltd.

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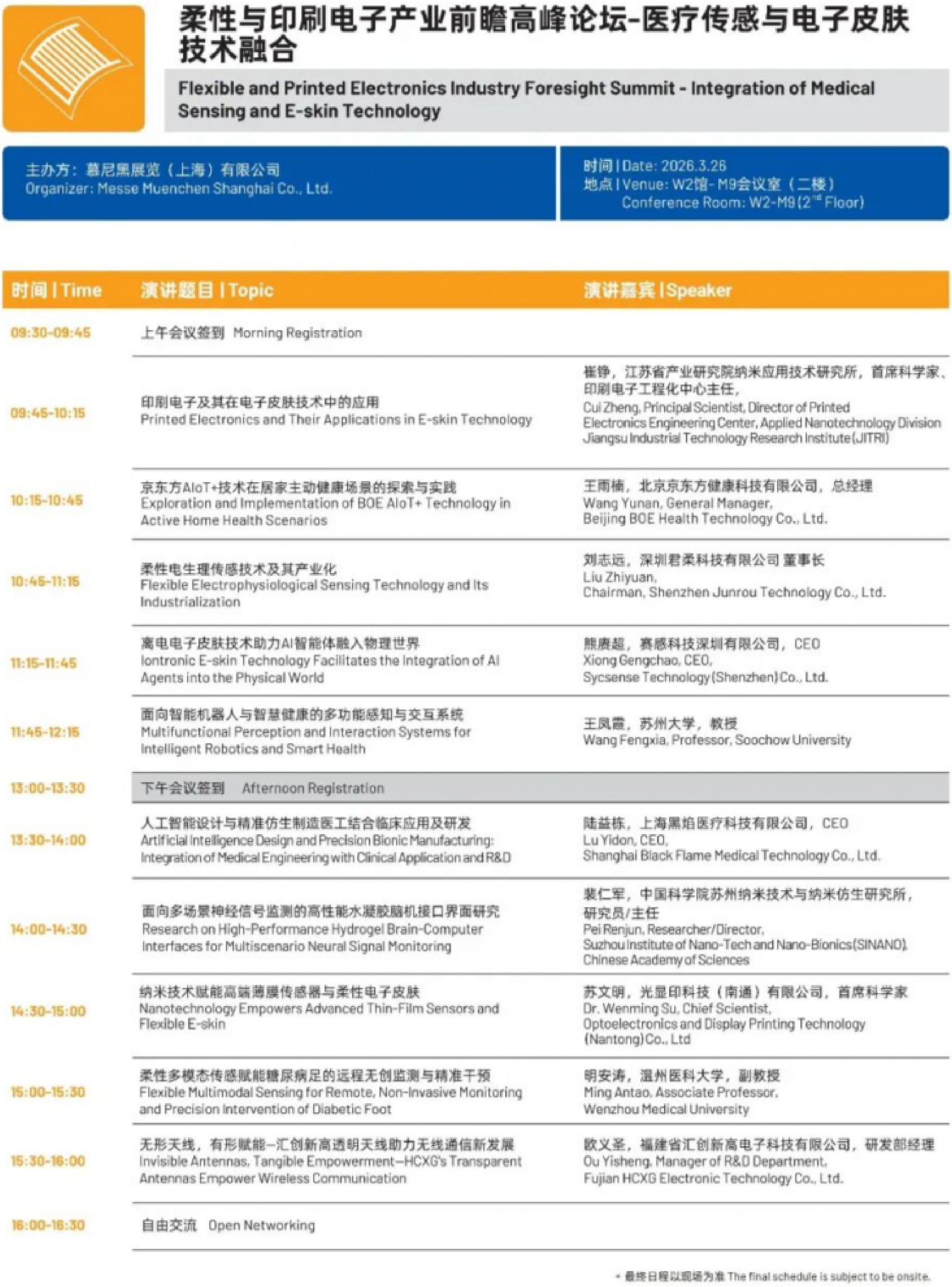

柔性与印刷电子产业前瞻高峰论坛-医疗传感与电子皮肤技术融合

Flexible and Printed Electronics Industry Foresight Summit - Integration of Medical Sensing and E-skin Technology

主办方：慕尼黑展览（上海）有限公司
Organizer: Messe Muenchen Shanghai Co., Ltd.

时间 | Date: 2026.3.26
地点 | Venue: W2馆- M9会议室（二楼）
Conference Room: W2-M9 (2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
09:30-09:45	上午会议签到 Morning Registration	
09:45-10:15	印刷电子及其在电子皮肤技术中的应用 Printed Electronics and Their Applications in E-skin Technology	崔铮，江苏省产业研究院纳米应用技术研究所，首席科学家、印刷电子工程化中心主任， Cui Zheng, Principal Scientist, Director of Printed Electronics Engineering Center, Applied Nanotechnology Division Jiangsu Industrial Technology Research Institute (JITRI)
10:15-10:45	京东方AIoT+技术在居家主动健康场景的探索与实践 Exploration and Implementation of BOE AIoT+ Technology in Active Home Health Scenarios	王雨楠，北京京东方健康科技有限公司，总经理 Wang Yunan, General Manager, Beijing BOE Health Technology Co., Ltd.
10:45-11:15	柔性电生理传感技术及其产业化 Flexible Electrophysiological Sensing Technology and Its Industrialization	刘志远，深圳君柔科技有限公司 董事长 Liu Zhiyuan, Chairman, Shenzhen Junrou Technology Co., Ltd.
11:15-11:45	离电子皮肤技术助力AI智能体融入物理世界 Iontronic E-skin Technology Facilitates the Integration of AI Agents into the Physical World	熊赓超，赛感科技深圳有限公司，CEO Xiong Gengchao, CEO, Sycsense Technology (Shenzhen) Co., Ltd.
11:45-12:15	面向智能机器人与智慧健康的多功能感知与交互系统 Multifunctional Perception and Interaction Systems for Intelligent Robotics and Smart Health	王凤霞，苏州大学，教授 Wang Fengxia, Professor, Soochow University
13:00-13:30	下午会议签到 Afternoon Registration	
13:30-14:00	人工智能设计与精准仿生制造医工结合临床应用及研发 Artificial Intelligence Design and Precision Bionic Manufacturing: Integration of Medical Engineering with Clinical Application and R&D	陆益栋，上海黑焰医疗科技有限公司，CEO Lu Yidon, CEO, Shanghai Black Flame Medical Technology Co., Ltd.
14:00-14:30	面向多场景神经信号监测的高性能水凝胶脑机接口界面研究 Research on High-Performance Hydrogel Brain-Computer Interfaces for Multiscenario Neural Signal Monitoring	裴仁军，中国科学院苏州纳米技术与纳米仿生研究所，研究员/主任 Pei Renjun, Researcher/Director, Suzhou Institute of Nano-Tech and Nano-Bionics (SINANO), Chinese Academy of Sciences
14:30-15:00	纳米技术赋能高端薄膜传感器与柔性电子皮肤 Nanotechnology Empowers Advanced Thin-Film Sensors and Flexible E-skin	苏文明，光显印科技（南通）有限公司，首席科学家 Dr. Wenming Su, Chief Scientist, Optoelectronics and Display Printing Technology (Nantong) Co., Ltd
15:00-15:30	柔性多模态传感赋能糖尿病足的远程无创监测与精准干预 Flexible Multimodal Sensing for Remote, Non-Invasive Monitoring and Precision Intervention of Diabetic Foot	明安涛，温州医科大学，副教授 Ming Antao, Associate Professor, Wenzhou Medical University
15:30-16:00	无形天线，有形赋能—汇创新高透明天线助力无线通信新发展 Invisible Antennas, Tangible Empowerment—HCXG's Transparent Antennas Empower Wireless Communication	欧义圣，福建省汇创新高电子科技有限公司，研发部经理 Ou Yisheng, Manager of R&D Department, Fujian HCXG Electronic Technology Co., Ltd.
16:00-16:30	自由交流 Open Networking	

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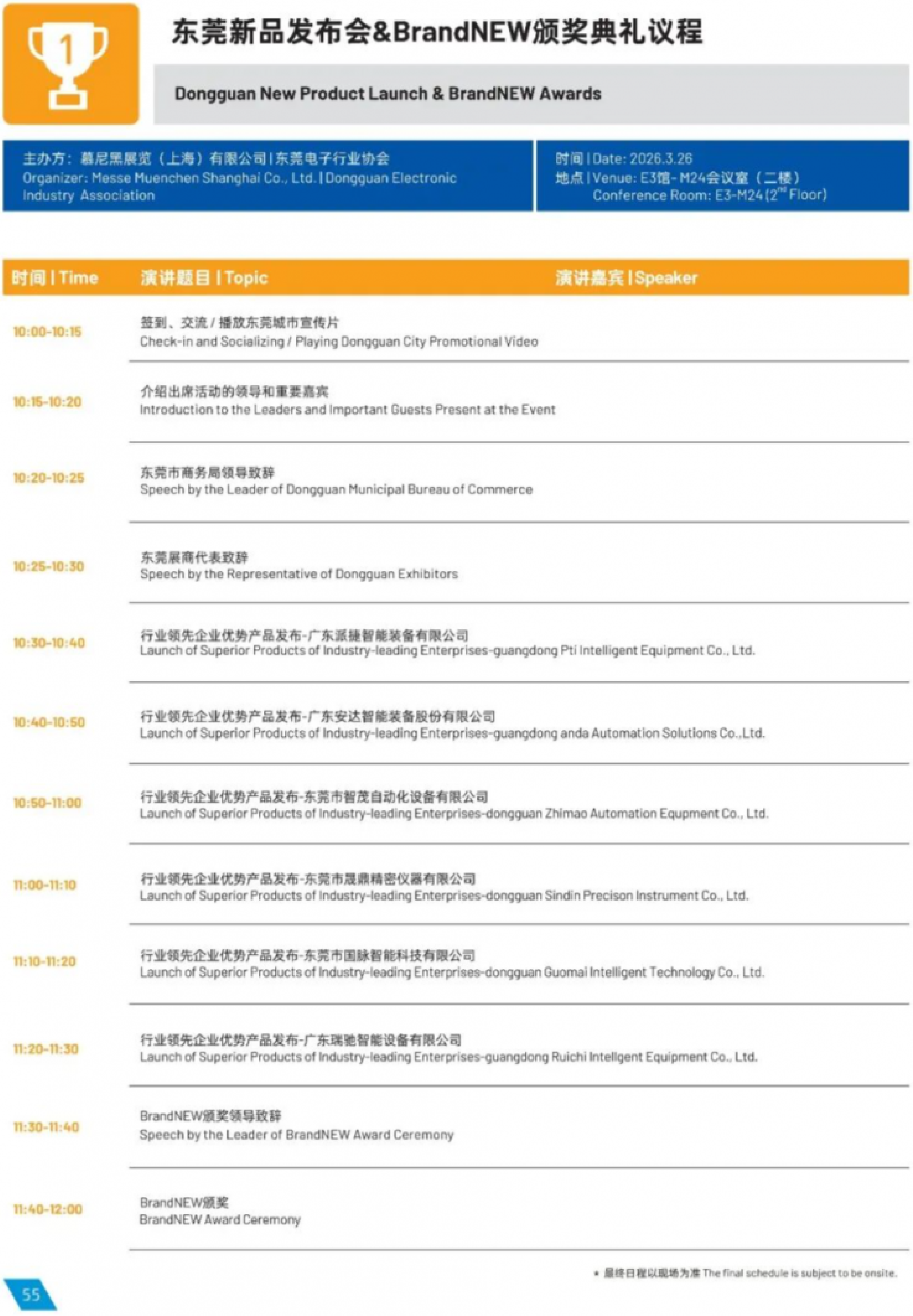

东莞新品发布会&BrandNEW颁奖典礼议程

Dongguan New Product Launch & BrandNEW Awards

主办方：慕尼黑展览（上海）有限公司 | 东莞电子行业协会
Organizer: Messe Muenchen Shanghai Co., Ltd. | Dongguan Electronic Industry Association

时间 | Date: 2026.3.26
地点 | Venue: E3馆-M24会议室（二楼）
Conference Room: E3-M24 (2nd Floor)

时间 | Time	演讲题目 | Topic	演讲嘉宾 | Speaker
10:00-10:15	签到、交流 / 播放东莞城市宣传片 Check-in and Socializing / Playing Dongguan City Promotional Video	
10:15-10:20	介绍出席活动的领导和重要嘉宾 Introduction to the Leaders and Important Guests Present at the Event	
10:20-10:25	东莞市商务局领导致辞 Speech by the Leader of Dongguan Municipal Bureau of Commerce	
10:25-10:30	东莞展商代表致辞 Speech by the Representative of Dongguan Exhibitors	
10:30-10:40	行业领先企业优势产品发布-广东派捷智能装备有限公司 Launch of Superior Products of Industry-leading Enterprises-guangdong Pti Intelligent Equipment Co., Ltd.	
10:40-10:50	行业领先企业优势产品发布-广东安达智能装备股份有限公司 Launch of Superior Products of Industry-leading Enterprises-guangdong anda Automation Solutions Co.,Ltd.	
10:50-11:00	行业领先企业优势产品发布-东莞市智茂自动化设备有限公司 Launch of Superior Products of Industry-leading Enterprises-dongguan Zhimao Automation Equpment Co., Ltd.	
11:00-11:10	行业领先企业优势产品发布-东莞市晟鼎精密仪器有限公司 Launch of Superior Products of Industry-leading Enterprises-dongguan Sindin Precison Instrument Co., Ltd.	
11:10-11:20	行业领先企业优势产品发布-东莞市国脉智能科技有限公司 Launch of Superior Products of Industry-leading Enterprises-dongguan Guomai Intelligent Technology Co., Ltd.	
11:20-11:30	行业领先企业优势产品发布-广东瑞驰智能设备有限公司 Launch of Superior Products of Industry-leading Enterprises-guangdong Ruichi Intellgent Equipment Co., Ltd.	
11:30-11:40	BrandNEW颁奖领导致辞 Speech by the Leader of BrandNEW Award Ceremony	
11:40-12:00	BrandNEW颁奖 BrandNEW Award Ceremony	

* 最终日程以现场为准 The final schedule is subject to be onsite.

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